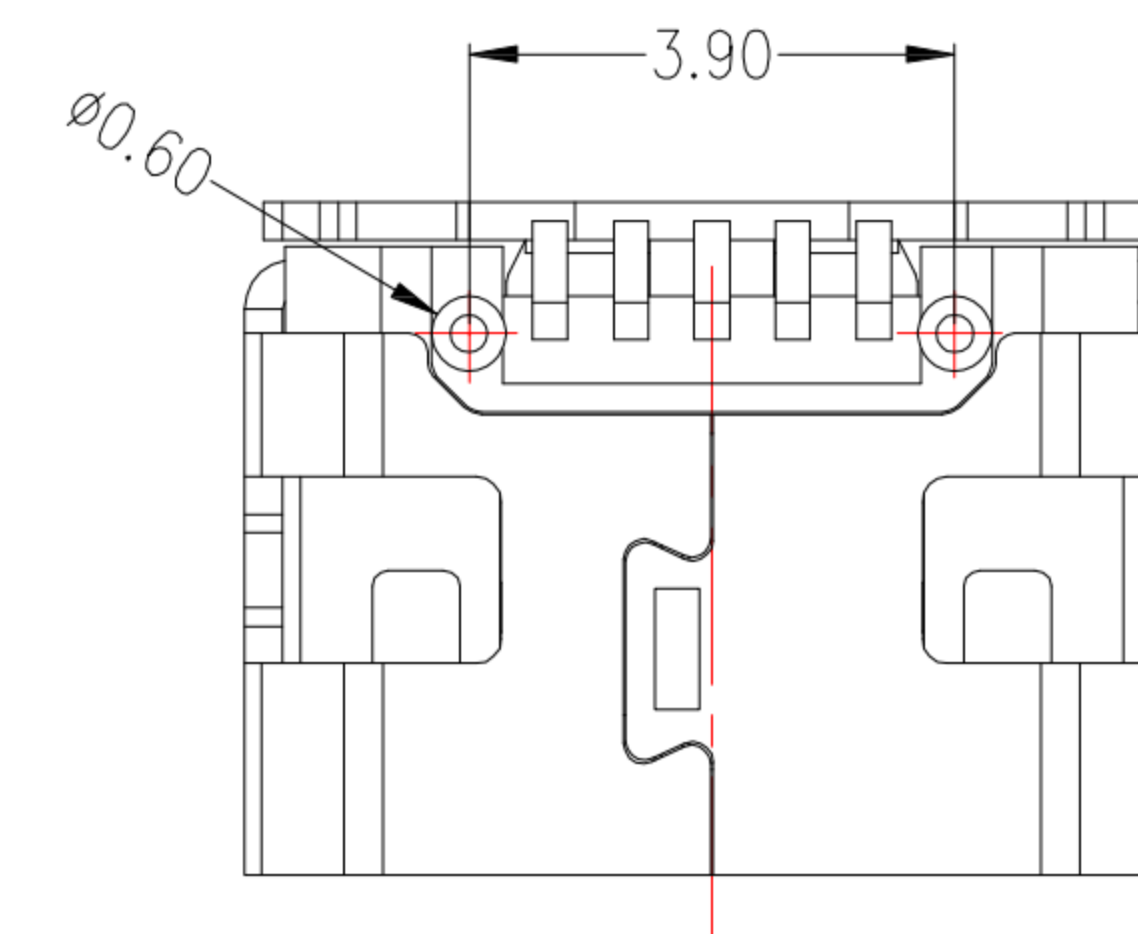
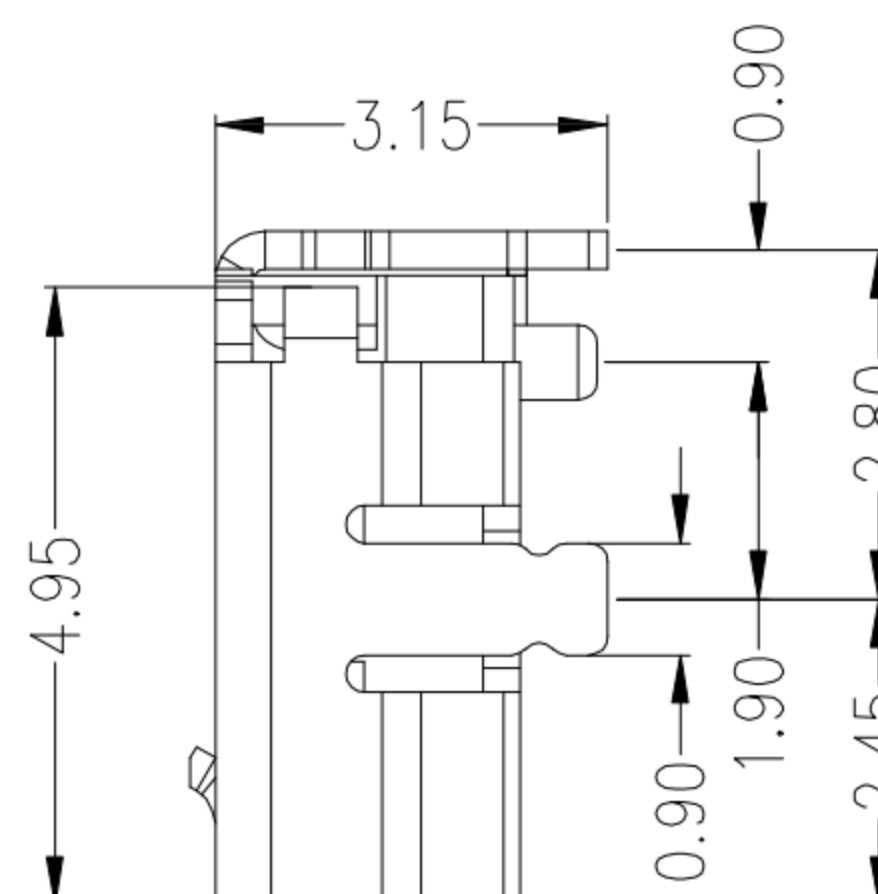
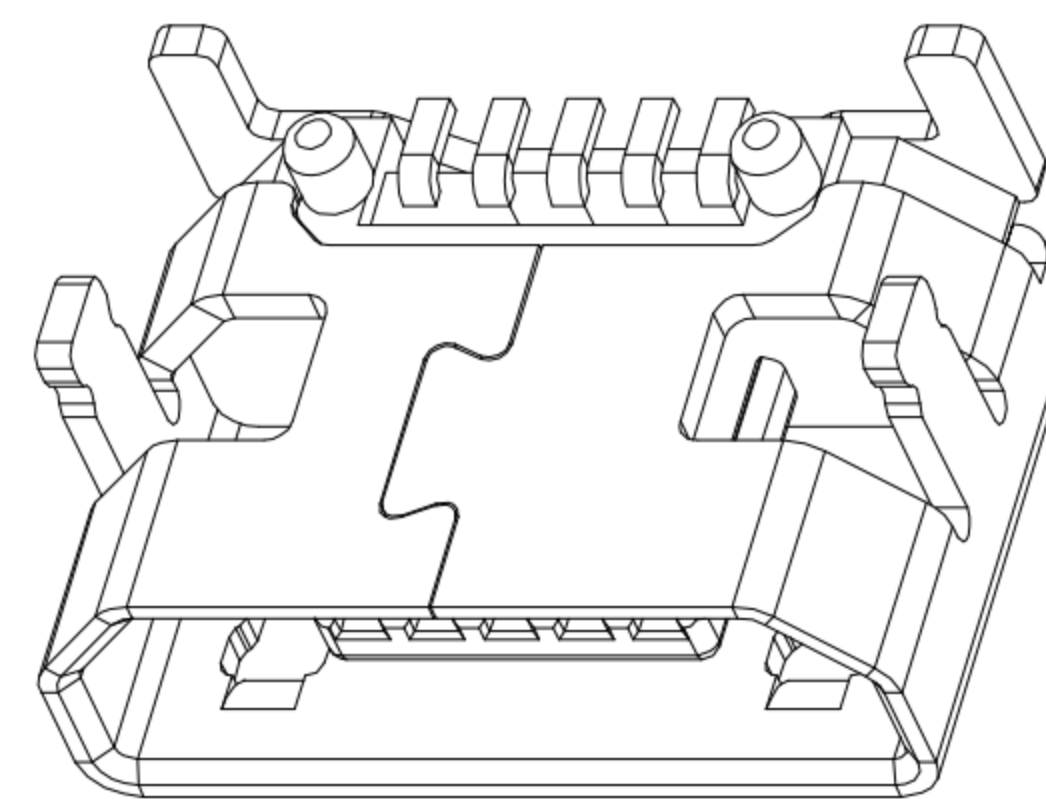
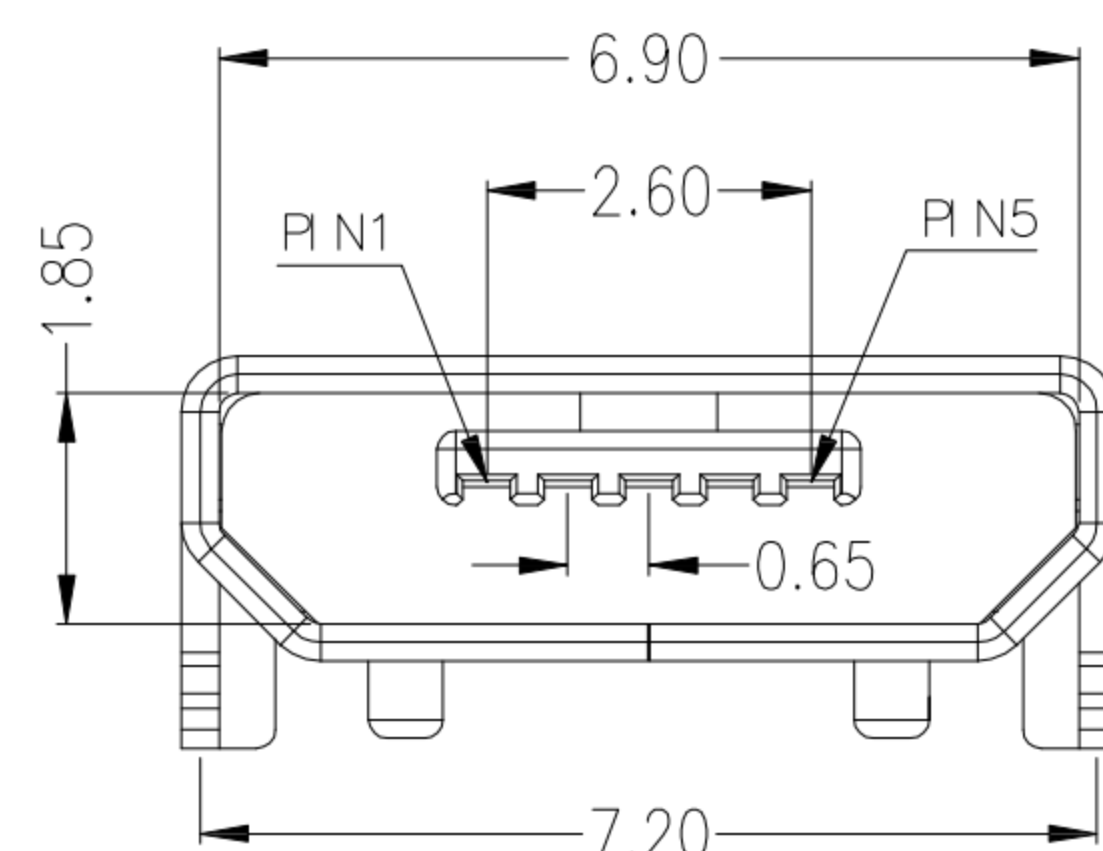
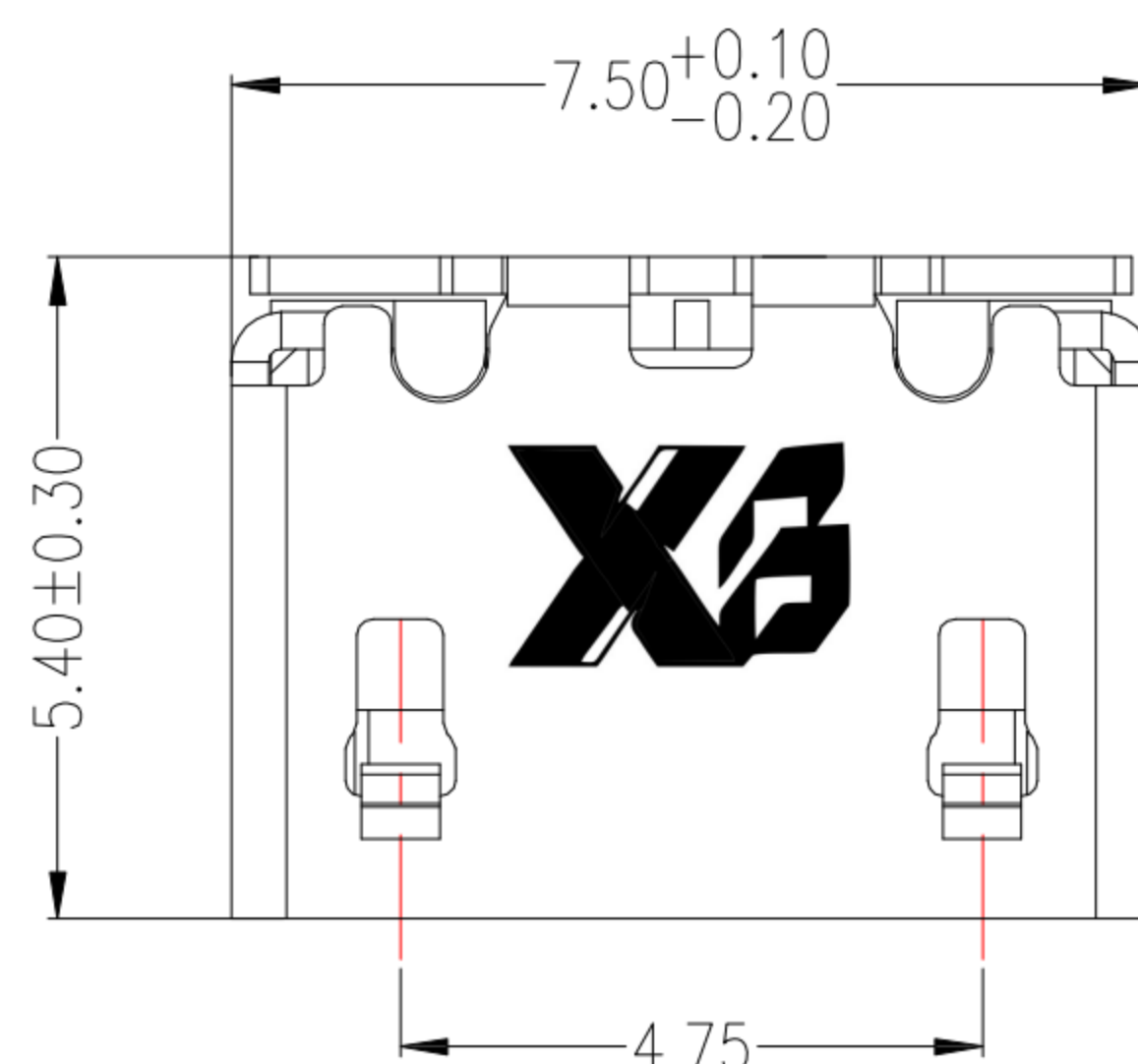
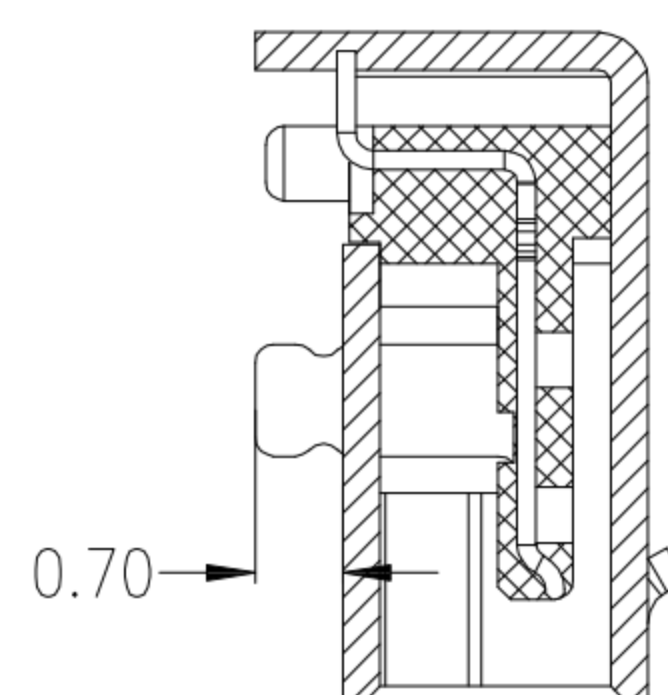


— SHELL鍍層:

TN
NI



NOTES:

1.MATERIAL:

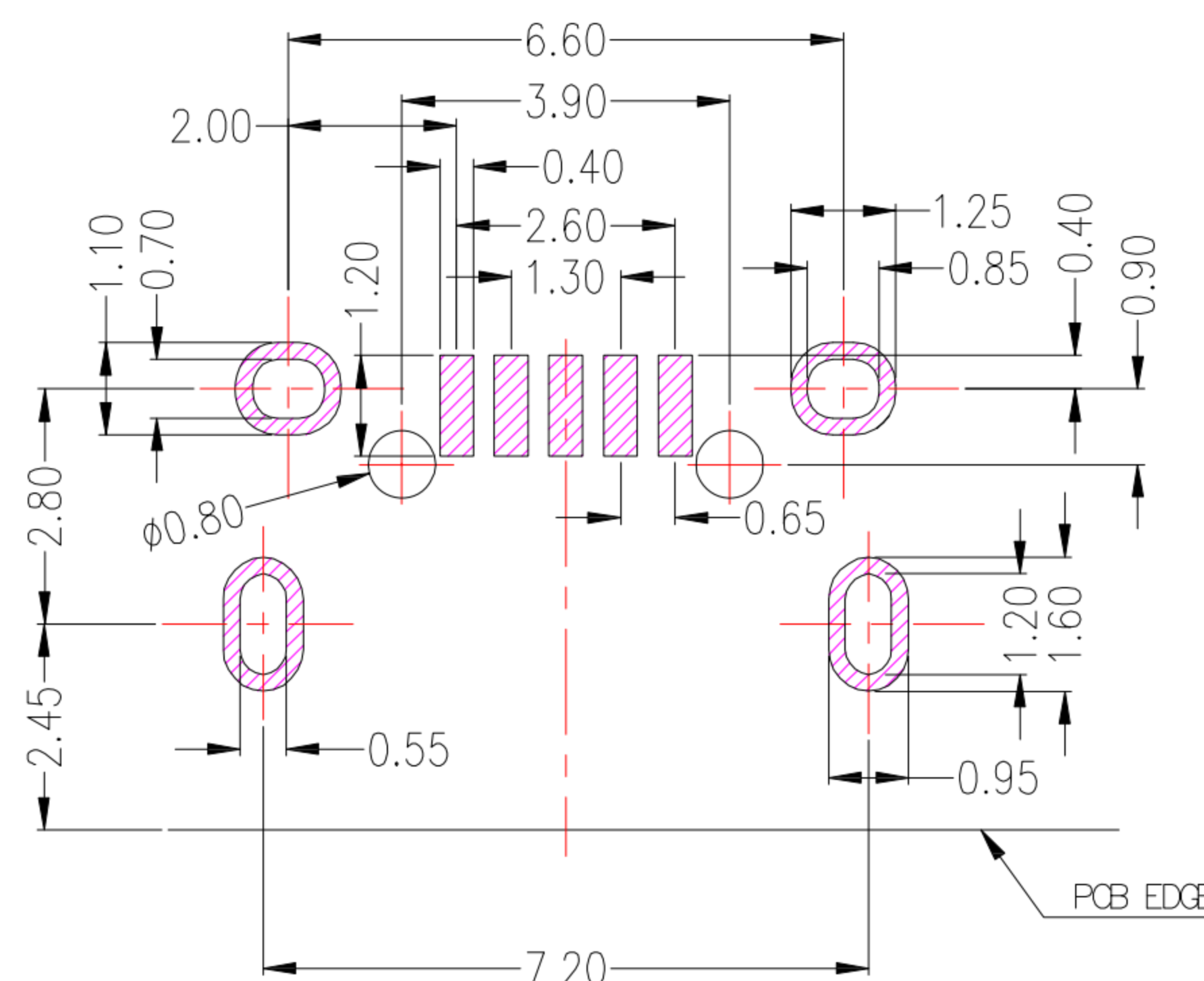
- 1.1 HOUSING: LCP
1.2 CONTACT: PHOSPHOR BRONZE
1.3 SHELL: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Tin or Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 CURRENT RATING: 1.8 A (PIN1,5) ; 1.0 A(PIN2,3,4)
- 3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C

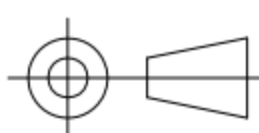


P.C.B LAYOUT MOUNTING PATTERN



TOLERANCE UNLESS OTHERWISE STATED :	Up to 5	± 0.2
	Above 5 ~ 15	± 0.3
	Above 15 ~ 30	± 0.4
	Above 30 ~ 50	± 0.5
	Angle	± 0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:	DATE
Jack Lu	08/02/18

CHECKED BY:	DATE
Jacky Chen	08/02/18

APPROVED BY:	DATE
Tony Kao	08/02/18

MAT'L

FINISH

SCALE

SHEET NO.

TITLE

MODLE

DWG NO

PART NO.

CONNECTOR

MICRO USB 5BF 牛角(PH7.2-6.6) 有柱,無捲邊

0. MRUSB5B-ED14Bx-S347

D. MRUSB5B-ED14Bx-S347

SIZE

	A4
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VER
B